

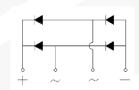
GBJ6B thru GBJ6G

Single Phase Glass Passivated Silicon Bridge Rectifier

 $V_{RRM} = 100 \text{ V} - 400 \text{ V}$ $I_{O} = 6 \text{ A}$

Features

- Epoxy Resin material compliant with 94V-0 standards of UL Material Flammability Provisions
- · Compliant with RoHS Provisions
- Single in-line DIP package, compact size
- · Low forward voltage, high forward current
- High surge current capability
- \bullet Types from 100 V to 400 V V_{RRM}
- · Small size, high heat-conducting performance
- Thermal welding performance: 260 °C/10 s
- Weight: 7.25 g (0.25 Oz)
- Not ESD Sensitive







Maximum ratings at $T_A = 25$ °C (ambient temperature), unless otherwise specified

Parameter	Symbol	Conditions	GBJ6B	GBJ6D	GBJ6G	Unit
Repetitive peak reverse v	oltage V _{RRM}		100	200	400	V
DC blocking voltage	V_{DC}		100	200	400	V
Operating temperature	T _j		-50 to 150	-50 to 150	-50 to 150	°C
Storage temperature	T _{stg}		-50 to 150	-50 to 150	-50 to 150	°C

Electrical characteristics at T_A = 25 °C, unless otherwise specified

Resistive load, single phase, half sine wave, 60 Hz.

For capacitive load derate current by 20%.

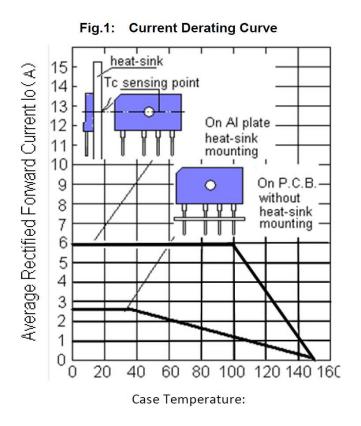
Parameter	Symbol	Conditions	GBJ6B	GBJ6D	GBJ6G	Unit
Maximum average forward rectified current	Io	T _C = 100 °C	6 ⁽¹⁾	6 ⁽¹⁾	6 ⁽¹⁾	Α
		T _A = 25 °C	2.7 (2)	2.7 ⁽²⁾	2.7 (2)	
Maximum forward surge current	I _{FSM}	8.3 ms pulse width, single pulse sine-wave, rated load, $T_j = 25$ °C	150	150	150	А
Maximum forward voltage	V_{F}	I _F = 3 A	1.05	1.05	1.05	V
Max. reverse current leakage a rated DC blocking voltage	t I _R	T _A = 25 °C	5	5	5	μΑ
		$T_A = 125 ^{\circ}C$	500	500	500	
Insulation strengthg (Lead wire to case)	$V_{\rm dis}$	AC Voltage: 1 minute, current leakage < 1 mA	2.5	2.5	2.5	kV
Fusing feature	l ² t	1ms ≤ t < 10ms, T _j =25 °C	80	80	80	A ² s
Thermal resistance	$R_{\Theta JA}$	without heatsink	26 ⁽²⁾	26 ⁽²⁾	26 ⁽²⁾	°C/W
	$R_{\Theta JC}$	with stated size heatsink	3.4 (1)	3.4 (1)	3.4 (1)	
Mounting torgue	TOR			1.0 (0.8 Nm is recomended)		

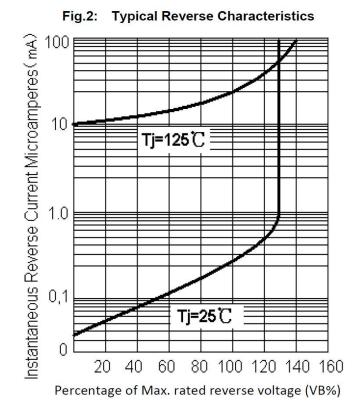
Remarks: (1) Install on PCB with stated size heat sink. In order to reach excellent heat dissipation performance, please coat thermal conductive sillica gel in moderation, use M3 screw to screw up. Recommended heatsink size: 8.2*8.2*3.0 cm.

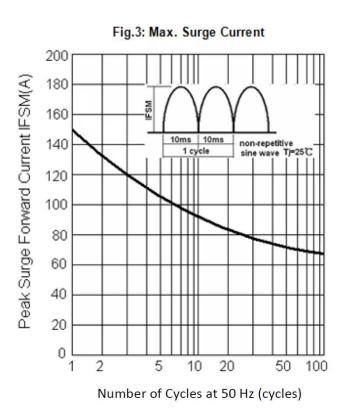
(2) Install on PCB without heatsink.

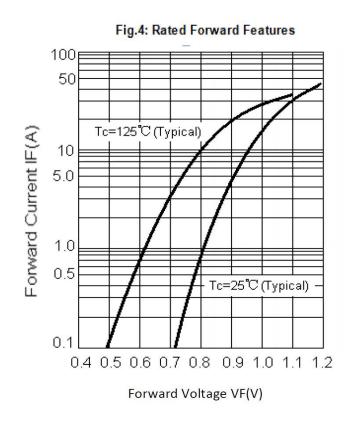














Package dimensions and terminal configuration

Product is marked with part number and terminal configuration.

